

In case of consideration for using Automotive equipment / device which demand high reliability, kindly contact our sales window correspondents.

APPLICABLE STANDARD		TEST METHOD		REQUIREMENTS		QT	AT
RATING	OPERATING TEMPERATURE RANGE	-55 °C TO 85 °C ⁽¹⁾	STORAGE TEMPERATURE RANGE	-10 °C TO 60 °C ⁽²⁾			
	VOLTAGE	100 V AC	STORAGE HUMIDITY RANGE	40 % TO 70 % ⁽²⁾			
CURRENT	0.5 A (SIGNAL CONTACT) ⁽³⁾		OPERATING HUMIDITY RANGE	RELATIVE HUMIDITY 85% max			
	3 A (MF CONTACT)			(NOT DEWED)			
SPECIFICATIONS							
ITEM	TEST METHOD			REQUIREMENTS			
CONSTRUCTION		VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.			
MARKING		CONFIRMED VISUALLY.					
ELECTRIC CHARACTERISTICS							
CONTACT RESISTANCE	100 mA(DC OR 1000Hz)	SIGNAL CONTACT : 90 mΩ MAX. MF CONTACT : 30 mΩ MAX.					
INSULATION RESISTANCE	250 V DC.	1000 MΩ MIN.					
VOLTAGE PROOF	300 V AC FOR 1 min.	NO FLASHOVER OR BREAKDOWN.					
MECHANICAL CHARACTERISTICS							
INSERTION AND WITHDRAWAL FORCES	MEASURED BY APPLICABLE CONNECTOR.		INSERTION FORCE: 50 N MAX. WITHDRAWAL FORCE: 5 N MIN.				
MECHANICAL OPERATION	500 TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX.				
			② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.				
VIBRATION	FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min SINGLE AMPLITUDE : 0.75 mm, 10 CYCLES FOR 3 DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1 μs.				
SHOCK	490 ms ² , DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.		② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.				
ENVIRONMENTAL CHARACTERISTICS							
DAMP HEAT (STEADY STATE)	EXPOSED AT 40±2 °C, 90 ~ 95 %, 96 h.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX.				
RAPID CHANGE OF TEMPERATURE	TEMPERATURE -55 → +85 °C TIME 30 → 30 min. UNDER 5 CYCLES. (RELOCATION TIME TO CHAMBER: WITHIN 2~3 MIN)		② INSULATION RESISTANCE : 1000 MΩ MIN.				
SULFUR DIOXIDE	EXPOSED AT 25±2°C, 75±5%RH, 25 PPM FOR 96 h. (TEST STANDARD: JIS C 60068)		③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.				
RESISTANCE TO SOLDERING HEAT	1) REFLOW SOLDERING : PEAK TMP : 260°C MAX REFLOW TMP : 220°C MIN FOR 60sec 2) SOLDERING IRONS : 360°C MAX. FOR 5 sec.		NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINAL.				
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE 240±3°C FOR IMMERSION DURATION, 3 sec.		A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.				
COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE			
REMARKS	⁽¹⁾ INCLUDE TEMPERATURE RISE CAUSED BY CURRENT-CARRYING.						
	⁽²⁾ "STORAGE" MEANS A LONG-TERM STORAGE STATE FOR THE UNUSED PRODUCT BEFORE ASSEMBLY TO PCB.						
	⁽³⁾ THE RATED CURRENT APPLIES TO PER CONTACT.						
Unless otherwise specified, refer to JIS-C-5402.							
Note QT: Qualification Test AT: Assurance Test X: Applicable Test		DRAWING NO.		ELC4-334384-00			
HRS	SPECIFICATION SHEET		PART NO.	FX18-80P-0.8SV10			
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL579-0024-8-00			
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